

ABSTRACT OF THE DISCLOSURE

Photoresist Stripping Composition and Method

An organic photoresist stripping composition and method of using the composition with silicon wafers having an insulating layer and metallization on the wafers, having an aryl sulfonic acid or alkylaryl sulfonic acid or mixtures thereof; 1,3-dihydroxybenzene (resorcinol) or sorbitol or mixtures thereof; one or more hydrocarbon solvents having a flash point of greater than about 65°C, and optionally less than about 0.5 % by weight water based on the total weight of the composition. The composition may also be used for the removal of other materials from other substrates.

10 [No suitable figure]